



Product Change Notification - KSRA-15IEHC532

Date:

14 Jan 2019

Product Category:

Ethernet PHYs

Affected CPNs:**Notification subject:**

CCB 3371 and 3371.001 Final Notice: Qualification of ASE as a new assembly site for selected Micrel products available in 48L (7x7x0.9mm) and 64L (8x8x0.9mm) VQFN packages.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of ASE as a new assembly site for selected Micrel products available in 48L (7x7x0.9mm) and 64L (8x8x0.9mm) VQFN packages.

Pre Change:

Assembled at TICIP assembly site

Post Change:

Assembled at ASE assembly site

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Taiwan IC Packing Corp. (TICP)	ASE Inc. (ASE)
Wire material	Au	Au
Die attach material	EN4900	EN4900
Molding compound material	G631	G631
Lead frame material	C194	C194

Impacts to Data Sheet:

None.

Change Impact:

None.

Reason for Change:

To improve manufacturability by qualifying ASE as new assembly site

Change Implementation Status:

In Progress

Estimated First Ship Date:

February 14, 2019 (date code: 1907)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:



Workweek	May 2018					-->	January 2019					February 2019			
	18	19	20	21	22		01	02	03	04	05	06	07	08	09
Initial PCN Issue Date				X											
Qual Report Availability							X								
Final PCN Issue Date							X								
Estimated Implementation Date												X			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report

Revision History:

May 21, 2018: Issued initial notification.

August 15, 2018: Re-issued initial notification to update affected CPN list by removing parts that uses Cu bond Wire.

January 14, 2019: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on February 14, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-15IEHC532_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

KSZ9031MNXCA
KSZ9031MNXCA-TR
KSZ9031MNXIA
KSZ9031MNXIA-TR
KSZ9031RNXCA
KSZ9031RNXCA-TR
KSZ9031RNXIA
KSZ9031RNXIA-TR
KSZ9031RNXIA-TR-JDR